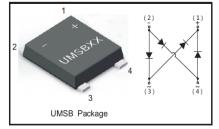
TD4UF40M

Surface Mount Fast Recovery Bridge Rectifier Reverse Voltage - 1000 V Forward Current - 4 A

Features

- · Glass passivated chip junction
- Fast reverse recovery time
- Designed for Surface Mount Application

PIN	DESCRIPTION				
1	Output Anode (+)				
2	Output Cathode (-)				
3	Input Pin (~)				
4	Input Pin (~)				



Mechanical Data

· Case: Molded plastic, UMSB

• Terminals: solderable per MIL-STD-750, Method 2026

Absolute Maximum Ratings and Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%.

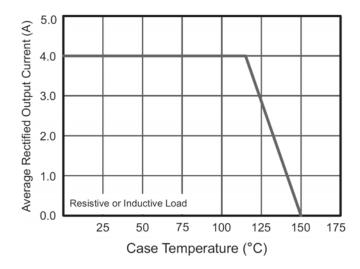
Develope	Symbols	Value	Units	
Parameter	Marking	UMB40M	-	
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	1000	V	
Maximum RMS Voltage	V _{RMS}	700	V	
Maximum DC Blocking Voltage	V_{DC}	V _{DC} 1000		
Average Rectified Output Current (at T _C = 115°C)	I _{F(AV)}	I _{F(AV)} 4		
Peak Forward Surge Current 8.3 ms Single Half-sine-wave Superimposed on Rated Load (JEDEC Method)	I _{FSM}	100	А	
Maximum Forward Voltage at 4 A	V_{F}	1.6	V	
Maximum DC Reverse Current at Rated DC $T_a = 25 ^{\circ}\text{C}$ Blocking Voltage DC Blocking Voltage $T_a = 125 ^{\circ}\text{C}$	I _R	5 100	μΑ	
Typical Junction Capacitance 1)	C _j	50	pF	
Typical Thermal Resistance ²⁾	$R_{\theta JA}$	40	°C/W	
Maximum Reverse Recovery Time 3)	t _{rr}	75	ns	
Operating Junction and Storage Temperature Range	T _j , T _{stg}	- 55 to + 150	°C	

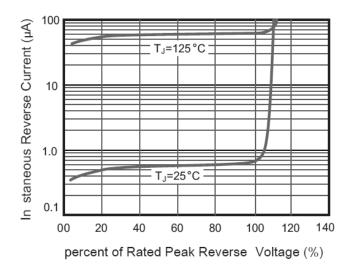
¹⁾ Measured at 1 MHz and applied reverse voltage of 4 V D.C.

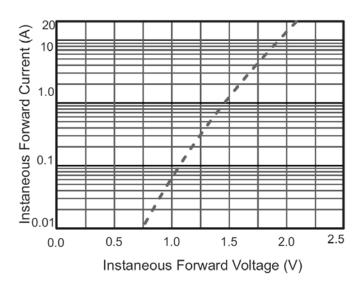


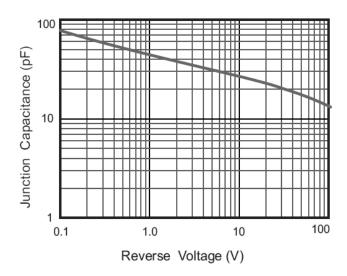
 $^{^{2)}}$ Mounted on glass epoxy PC board with 4 × 1.5" × 1.5" (3.81 × 3.81 cm) copper pad.

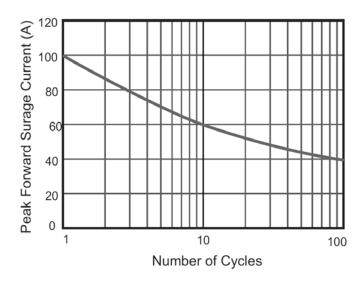
 $^{^{3)}}$ Measured with I = 0.5 A, I_R = 1 A, Irr = 0.25 A .









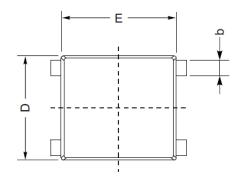


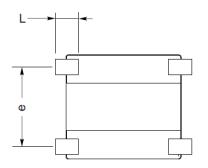


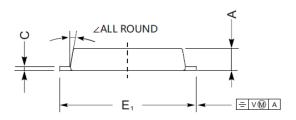
PACKAGE OUTLINE

Plastic surface mounted package; 4 leads

UMSB







UNIT	А	С	D	E	E ₁	L	е	b	
mm	1.5	0.29	7	7.6	8.9	1.6	5.3	1.15	10°
	1.3	0.17	6.2	7.1	7.9	1	4.9	0.95	

